

1. General Requirements

All components have to be mounted according to the drawing: GAA26800MX
The bare board is specified as: GAA610ADB

2. Revision History

Version	Date	Revised by	Description
1.0	2010-APR-13	A. Tutat	Initial Version

3. Code Requirements

The board has been laid out according to the requirements in EN81, VDE110-1 (Transient Voltage 4kV; Inhomogeneous Field, Pollution Degree 2 and Safety relevant areas to other areas: Pollution Degree 3; Clearance Distance: Table2; Creepage Distance: Table

Date	Changes	Name	Test Requirement for PBX_BIDI	GAA26800MX_TR		
				12 SHEETS - SHEET 1		
				RESP	2010-APR-13	A. Tutat
			OTIS Elevator Company Enigneering Center Berlin	CHK	2010-APR-13	M. Dehmlow
				AUT	2010-APR-13	CA47A-000528

4. Data logging Requirements for the purpose of statistical analysis.

All measurement results should be written together with the PCB serial number and production-date into a file.
The time-interval to produce a back-up of the file should be determined by the factory. Also must be determined how many records are captured per file.

Construction of the file:

1. PCB serial number
 2. production-date
 3. all measurement results, The variable-names should consist of a combination of Symbol-Name and Parameter-Name.)
- Visual separation through special character, for example: *****.

5. Electrical Requirements

Unless otherwise noted MIN/MAX values are valid for temperatures between +0degC and +70degC.
All typical values are calculated for an ambient temperature of Ta=25degC.

DC values have to be measured with an average reading meter. AC values have to be measured with a true-RMS meter.
DC values are marked with the unit V or A, AC values are marked with Vrms or Arms.

The remark "Logic Level" (LL) relates to HCMOS standard: "High" = 3.5V ... 5.7V and "Low"=-0.7V ... 1.0V.

Date	Changes	Name	Test Requirement for PBX_BIDI	GAA26800MX_TR		
				12 SHEETS - SHEET 2		
			OTIS Elevator Company Enigneering Center Berlin	RESP	2010-APR-13	A. Tutat
				CHK	2010-APR-13	M. Dehmlow
				AUT	2010-APR-13	CA47A-000528

5.1. Power supply

If within the test cases no other supply voltages are indicated,
the board has to be supplied with the following voltages:

24V_HL2 +24V / current limitable to max. 500mA at P5.46 (referenced to HL2)
HL2 at P5.44

24V_SE +24V / current limitable to max. 500mA at P1.1 (referenced to 24V_SE_RTN)
24V_SE_RTN at P1.2

24V_SW +24V / current limitable to max. 500mA at P4.1 (referenced to 24V_SW_RTN)
24V_SW_RTN at P4.2

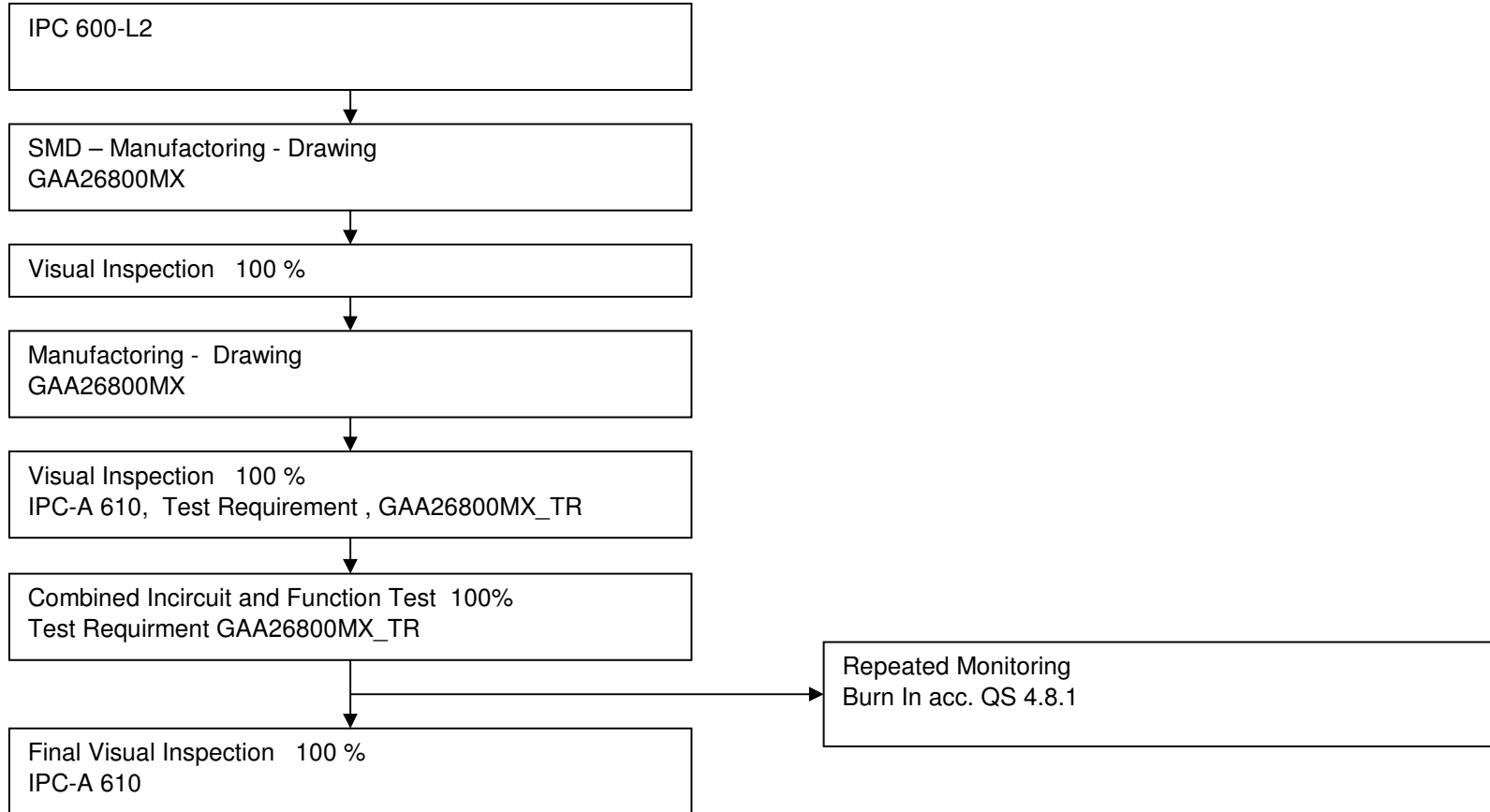
24V_SENSE +24V / current limitable to max. 500mA at P5.50 (referenced to 24V_SENSE_RTN)
24V_SENSE_RTN at P5.48

V+15V +15V / current limitable to max. 200mA at P3.40 (referenced to AGND)
V-15V -15V / current limitable to max. 200mA at P3.39 (referenced to AGND)
AGND at P3.38

VCC +5V / current limitable to max. 200mA at P3.13 (referenced to GND)
GND at P3.12

Date	Changes	Name	Test Requirement for PBX_BIDI	GAA26800MX_TR		
				12 SHEETS - SHEET 3		
				RESP	2010-APR-13	A. Tutat
			OTIS Elevator Company Enigneering Center Berlin	CHK	2010-APR-13	M. Dehmlow
				AUT	2010-APR-13	CA47A-000528

6. Test Flow



Date	Changes	Name	Test Requirement for PBX_BIDI	GAA26800MX_TR		
				12 SHEETS - SHEET 4		
			OTIS Elevator Company Enigneering Center Berlin	RESP	2010-APR-13	A. Tutat
				CHK	2010-APR-13	M. Dehmlow
				AUT	2010-APR-13	CA47A-000528

Test Requirement for PBX_BIDI GAA26800MX					Samples												Value range					
1. All measuring instruments must be calibrated!!! 2. As an additional document, the circuit diagram of the PCBA is required. 3. All measuring points : reference points are described in kind of netnames, test points or component designator. 4. PBX_BIDI alternatively assembled with CONVERTER- or INVERTER-FUNCTIONALITY test cases only for PBX_BIDI, INVERTER -FUNCTIONALITY, GAA26800 MX1 , marked with note: 1 test cases only for PBX_BIDI, CONVERTER -FUNCTIONALITY, GAA26800 MX2 , marked with note: 2 5. Highly Accelerated Life Test, test cases required for HALT , marked with note: 3																	Lower Specification Limit			Upper Specification Limit		
Test cases					Board Serial Number												LSL	Typical	USL			
Description	note	note	measuring point : reference point @ specified condition	unit																		
Power Supply: IGBT Gate Driver PHASE R(U)	1		quiescent current consumption: 24V_SW @ 24VDC current: IGBT driver SMPS	mA											180,00	236,00	290,00					
SMPS characteristic Switched Mode Power Supply	2		quiescent current consumption: 24V_SE @ 24VDC current: IGBT driver SMPS, SENSING SMPS													180,00	236,00	290,00				
Power Fail Detection			PWM_VCC_RU : 24V_DRIVER_RTN	V											10,00	11,00	13,00					
			I_SENSE_RU : 24V_DRIVER_RTN												0,30	0,60	0,80					
			SWITCHING ON-DUTY-CYCLE w/o any additional load PWM CONTROLLER output pin or MOSFET DRAIN GATE_SENSE_RU : 24_DRIVER_RTN DRAIN_RU : 24_DRIVER_RTN	%											5,00	20,00	30,00					
			SWITCHING FREQUENCY PWM CONTROLLER output pin or MOSFET DRAIN GATE_SENSE_RU : 24_DRIVER_RTN DRAIN_RU : 24_DRIVER_RTN	kHz											140,00	160,00	180,00					
	3		+27V_RU_P : +27V_RU_P_RTN	V											26,00	27,00	28,00					
	3		+27V_RU_N : +27V_RU_N_RTN													26,00	27,00	28,00				
			REF_3V9_RU_P : +27V_RU_P_RTN													6,50	7,00	7,50				
			REF_2V5_RU_P : +27V_RU_P_RTN													2,38	2,50	2,63				
			PF_IGBT threshold voltage Increase +27V_RU_P from 0V until output a transition occurs: HIGH to LOW MX1: PF_IGBT_INV : GND MX2: PF_IGBT_CONV : GND preparation: disconnect primary 24V_SW and 24V_SE supply, add an adjustable supply only on +27V_RU_P referenced to +27V_RU_P_RTN												2,00	2,40	2,80					
			REF_3V9_RU_N : +27V_RU_N_RTN													6,50	7,00	7,50				
			REF_2V5_RU_N : +27V_RU_N_RTN													2,38	2,50	2,63				
			PF_IGBT threshold voltage Increase +27V_RU_N from 0V until output a transition occurs: HIGH to LOW MX1: PF_IGBT_INV : GND MX2: PF_IGBT_CONV : GND preparation: disconnect primary 24V_SW and 24V_SE supply, add an adjustable supply only on +27V_RU_N referenced to +27V_RU_N_RTN													2,00	2,40	2,80				



Test Requirement for PBX_BIDI GAA26800MX																	
1. All measuring instruments must be calibrated!!! 2. As an additional document, the circuit diagram of the PCBA is required. 3. All measuring points : reference points are described in kind of netnames, test points or component designator. 4. PBX_BIDI alternatively assembled with CONVERTER- or INVERTER-FUNCTIONALITY test cases only for PBX_BIDI, INVERTER -FUNCTIONALITY, GAA26800 MX1 , marked with note: 1 test cases only for PBX_BIDI, CONVERTER -FUNCTIONALITY, GAA26800 MX2 , marked with note: 2 5. Highly Accelerated Life Test, test cases required for HALT , marked with note: 3					Samples										Value range Lower Specification Limit Upper Specification Limit		
Test cases																	
Description	note	note	measuring point : reference point @ specified condition	unit													
Power Supply: IGBT Gate Driver PHASE S(V) SMPS characteristic Switched Mode Power Supply Power Fail Detection			PWM_VCC_SV : 24V_DRIVER_RTN	V										10,00	11,00	13,00	
			I_SENSE_SV : 24V_DRIVER_RTN											0,30	0,60	0,80	
			SWITCHING ON-DUTY-CYCLE w/o any additional load											5,00	20,00	30,00	
			PWM CONTROLLER output pin or MOSFET DRAIN	%													
			GATE_SENSE_SV : 24_DRIVER_RTN														
			DRAIN_SV : 24_DRIVER_RTN														
			SWITCHING FREQUENCY														
			PWM CONTROLLER output pin or MOSFET DRAIN	kHz										140,00	160,00	180,00	
			GATE_SENSE_RU : 24_DRIVER_RTN														
			DRAIN_RU : 24_DRIVER_RTN														
	3		+27V_SV_P : +27V_SV_P_RTN	V										26,00	27,00	28,00	
	3		+27V_SV_N : +27V_SV_N_RTN											26,00	27,00	28,00	
			REF 3V9_SV_P : +27V_SV_P_RTN											6,50	7,00	7,50	
			REF 2V5_SV_P : +27V_SV_P_RTN											2,38	2,50	2,63	
			PF_IGBT threshold voltage											2,00	2,40	2,80	
			Increase +27V_SV_P from 0V until output a transition occurs: HIGH to LOW														
			MX1: PF_IGBT_INV : GND														
			MX2: PF_IGBT_CONV : GND														
			preparation:														
			disconnect primary 24V_SW and 24V_SE supply,														
		add an adjustable supply only on															
		+27V_SV_P referenced to +27V_SV_P_RTN															
		REF 3V9_SV_N : +27V_SV_N_RTN											6,50	7,00	7,50		
		REF 2V5_SV_N : +27V_SV_N_RTN											2,38	2,50	2,63		
		PF_IGBT threshold voltage											2,00	2,40	2,80		
		Increase +27V_SV_N from 0V until output a transition occurs: HIGH to LOW															
		MX1: PF_IGBT_INV : GND															
		MX2: PF_IGBT_CONV : GND															
		preparation:															
		disconnect primary 24V_SW and 24V_SE supply,															
		add an adjustable supply only on															
		+27V_SV_N referenced to +27V_SV_N_RTN															

Test Requirement for PBX_BIDI GAA26800MX																			
1. All measuring instruments must be calibrated!!! 2. As an additional document, the circuit diagram of the PCBA is required. 3. All measuring points : reference points are described in kind of netnames, test points or component designator. 4. PBX_BIDI alternatively assembled with CONVERTER- or INVERTER-FUNCTIONALITY test cases only for PBX_BIDI, INVERTER-FUNCTIONALITY , GAA26800MX1, marked with note: 1 test cases only for PBX_BIDI, CONVERTER-FUNCTIONALITY , GAA26800MX2, marked with note: 2 5. Highly Accelerated Life Test, test cases required for HALT , marked with note: 3						Samples										Value range Lower Specification Limit Upper Specification Limit			
Test cases																			Board Serial Number
Description	note	note	measuring point : reference point @ specified condition	unit															
Power Supply: SENSING	1		quiescent current consumption: 24V_SENSE @ 24VDC current: SENSING SMPS	mA												20,00	100,00	200,00	
SMPS characteristic Switched Mode Power Supply			VCC_PWM_CONTROLLER : 24V_SMPS_SENSE_RTN	V												10,00	12,00	14,00	
			I_SENSE_PWM_CONTROLLER : 24V_SMPS_SENSE_RTN													0,30	0,60	0,80	
	1		SWITCHING ON-DUTY-CYCLE PWM CONTROLLER output pin or MOSFET DRAIN SMPS_SENSE_GATE : 24V_SMPS_SENSE_RTN SMPS_SENSE_DRAIN : 24V_SMPS_SENSE_RTN	%												22,00	27,00	32,00	
	2		SWITCHING ON-DUTY-CYCLE PWM CONTROLLER output pin or MOSFET DRAIN SMPS_SENSE_GATE : 24V_SMPS_SENSE_RTN SMPS_SENSE_DRAIN : 24V_SMPS_SENSE_RTN	%												34,00	39,00	44,00	
			SWITCHING FREQUENCY PWM CONTROLLER output pin or MOSFET DRAIN SMPS_SENSE_GATE : 24V_SMPS_SENSE_RTN SMPS_SENSE_DRAIN : 24V_SMPS_SENSE_RTN	kHz												140,00	160,00	180,00	
	3		InvTempUref (Addr.: 0x10) CnvTempUref (Addr.: 0x10) measuring point: S+15V / SGND signal: +15V_SENSE / GND_SENSE	mV												14250,00	15000,00	15750,00	
	3		-15V_SENSE : GND_SENSE													-15750,00	-15000,00	-14250,00	
Power Supply: PTC Temperature Measurement	1		quiescent current consumption: 24V_HL2 @ 24VDC current: SENSING SMPS	mA												20,00	100,00	200,00	
SMPS characteristic Switched Mode Power Supply			SW_TEMP_SENSOR : HL2	kHz												180,00	200,00	220,00	
	3		5V_HL2 : HL2													4,75	5,00	5,25	
preparation: Please connect, the test cases referred resistors between the inputs: PTC_1 and PTC_6			PTC_ADC: HL2 @ open PTC_1/PTC_6	V												3,00	3,70	5,00	
			PTC_ADC: HL2 @ 1k, 1% resistor between PTC_1/PTC_6													1,00	1,20	1,80	
			PTC_ADC: HL2 @ SHORT-CIRCUIT PTC_1/PTC_6													0,00	0,32	0,50	
			PTC_1 : PTC_6	mA												4,00	4,60	5,60	
DC-Link-LED acquisition via a LED sensor			Pilot LED flashing Frequency	Hz												5,00	7,00	15,00	
IGBT Gate Driver voltages			RUP_G11:RUP_E11@PWM_RP, PWM_UP=HIGH:GND	V												-16,00	-9,50	-5,00	
preparation: 1.) All drivers must be stimulated such that a connected IGBT would be switched on. Add an IGBT Gate-Emitter load, a 100nF±10% ceramic or metal foil capacitor must be connected between the measuring points: IGBT Gate to IGBT Emitter RUP_G11 : RUP_E11, RUN_G21 : RUN_E21 SVP_G11 : SVP_E11, SVN_G21 : SVN_E21 TWP_G11 : TWP_E11, TWN_G21 : TWN_E21			RUP_G11:RUP_E11@PWM_RP, PWM_UP=LOW:GND													14,00	15,70	17,00	
			RUN_G21:RUN_E21@PWM_RN, PWM_UN=HIGH:GND														-16,00	-9,50	-5,00
			RUN_G21:RUN_E21@PWM_RN, PWM_UN=LOW:GND														14,00	15,70	17,00
			SVP_G11:SVP_E11@PWM_SP, PWM_VP=HIGH:GND														-16,00	-9,50	-5,00
short circuit: IGBT Collector to IGBT Emitter RUP_C1 : RUP_E11 : RUN_E21 SVP_C1 : SVP_E11 : SVN_E21 TWP_C1 : TWP_E11 : TWN_E21			SVP_G11:SVP_E11@PWM_SP, PWM_VP=LOW:GND														14,00	15,70	17,00
			SVN_G21:SVN_E21@PWM_SN, PWM_VN=HIGH:GND														-16,00	-9,50	-5,00
			SVN_G21:SVN_E21@PWM_SN, PWM_VN=LOW:GND														14,00	15,70	17,00
			TWP_G11:TWP_E11@PWM_TP, PWM_WP=HIGH:GND														-16,00	-9,50	-5,00
2.) only GAA26800MX2 OUT_EN_CONV:GND set to HIGH level			TWP_G11:TWP_E11@PWM_TP, PWM_WP=LOW:GND														14,00	15,70	17,00
			TWN_G21:TWN_E21@PWM_TN, PWM_WN=HIGH:GND														-16,00	-9,50	-5,00
			TWN_G21:TWN_E21@PWM_TN, PWM_WN=LOW:GND														14,00	15,70	17,00

Test Requirement for PBX_BIDI GAA26800MX					Samples												Value range					
1. All measuring instruments must be calibrated!!! 2. As an additional document, the circuit diagram of the PCBA is required. 3. All measuring points : reference points are described in kind of netnames, test points or component designator. 4. PBX_BIDI alternatively assembled with CONVERTER- or INVERTER-FUNCTIONALITY test cases only for PBX_BIDI, INVERTER -FUNCTIONALITY, GAA26800MX1, marked with note: 1 test cases only for PBX_BIDI, CONVERTER -FUNCTIONALITY, GAA26800MX2, marked with note: 2 5. Highly Accelerated Life Test, test cases required for HALT , marked with note: 3																	Lower Specification Limit			Upper Specification Limit		
Test cases																	Board Serial Number					
Description	note	note	measuring point : reference point @ specified condition	unit																		
DRIVER_RESET_N logic low pulse width Description of the function: HCPL316J FAULT* changes from a high impedance state to a logic low, if the voltage on the HCPL316J DESAT pin exceeding an internal reference voltage of 7.5V while the IGBT is on. HCPL316J FAULT* output remains low until HCPL316J RESET* is brought low. HCPL316J FAULT* output is an open collector which allows the FAULT* outputs from all HCPL-316Js to be connected together in a "wired OR" forming the signals: GAA26800MX1: OCT_INV referenced to GND GAA26800MX2: CNV_OC_FLT referenced to GND When one of the six HCPL316J FAULT* outputs change to low, the HCPL316J RESET* input will change to low after a time delay of the "DRIVER_RESET_N logic low pulse width" preparation: 1.) All drivers must be stimulated such that a connected IGBT would be switched on. PWM_RP=LOW:GND, PWM_UP=LOW:GND PWM_RN=LOW:GND, PWM_UN=LOW:GND PWM_SP=LOW:GND, PWM_VP=LOW:GND PWM_SN=LOW:GND, PWM_VN=LOW:GND PWM_TP=LOW:GND, PWM_WP=LOW:GND PWM_TN=LOW:GND, PWM_WN=LOW:GND 2.) Add an IGBT Gate-Emitter load, a 100nF±10% ceramic or metal foil capacitor must be connected between the measure points: IGBT Gate to IGBT Emitter RUP_G11 : RUP_E11, RUN_G21 : RUN_E21 SVP_G11 : SVP_E11, SVN_G21 : SVN_E21 TWP_G11 : TWP_E11, TWN_G21 : TWN_E21 3.) Realize the following possibility to change between: short circuit / open for approximate 1ms: IGBT Collector to IGBT Emitter RUP_C1 : RUP_E11, RUP_E11 : RUN_E21 SVP_C1 : SVP_E11, SVP_E11 : SVN_E21 TWP_C1 : TWP_E11, TWP_E11 : TWN_E21 4.) only GAA26800MX2 OUT_EN_CONV:GND set to HIGH level stimulation: DESAT pins are executed successively by open only one of the short circuit "IGBT Collector to IGBT Emitter" for approximate 1ms. Keep a wait time condition to the next test case of approximate 500ms. All tests must be processed 2 times sequentially, in order to guarantee that no latch up effect appears.			GAA26800MX1: OCT_INV referenced to GND GAA26800MX2: CNV_OC_FLT referenced to GND HIGH pulse width @open <u>only</u> short circuit RUP_C1 : RUP_E11												200	360	450					
			GAA26800MX1: OCT_INV referenced to GND GAA26800MX2: CNV_OC_FLT referenced to GND HIGH pulse width @open <u>only</u> short circuit RUP_E11 : RUN_E21													200	360	450				
			GAA26800MX1: OCT_INV referenced to GND GAA26800MX2: CNV_OC_FLT referenced to GND HIGH pulse width @open <u>only</u> short circuit SVP_C1 : SVP_E11													200	360	450				
			GAA26800MX1: OCT_INV referenced to GND GAA26800MX2: CNV_OC_FLT referenced to GND HIGH pulse width @open <u>only</u> short circuit SVP_E11 : SVN_E21	ms												200	360	450				
			GAA26800MX1: OCT_INV referenced to GND GAA26800MX2: CNV_OC_FLT referenced to GND HIGH pulse width @open <u>only</u> short circuit TWP_C1 : TWP_E11													200	360	450				
			GAA26800MX1: OCT_INV referenced to GND GAA26800MX2: CNV_OC_FLT referenced to GND HIGH pulse width @open <u>only</u> short circuit TWP_E11 : TWN_E21													200	360	450				

Test Requirement for PBX_BIDI GAA26800MX																														
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Test cases																														
Description	note	note	measuring point : reference point @ specified condition	unit	Board Serial Number												LSL	Typical	USL											
POWER FAIL MONITORING thresholds PFAIL_RS_CONV signal changes from 1.) statical LOW level 2.) TOGGLE between LOW and HIGH 3.) statical HIGH level Umax_line_to_line=480V*1.1 resultant max. voltage range: ±3.7V (Vpp=7.4V) Umin_line_to_line=340V resultant min. voltage: Vpp=4.76V preparation: adjustable sinus voltage supply 7.4Vpp@50Hz, offset=0V to US / GND_SENSE	2		PFAIL_RS_CONV / GND threshold toggle Decrease US from 7.4Vpp until PFAIL_RS_CONV threshold changes from statical LOW to TOGGLE PFAIL_RS_CONV / GND threshold statical LOW Decrease US from 7.4Vpp until PFAIL_RS_CONV threshold changes from TOGGLE to statical HIGH	Vpp												1,00	1,30	4,76												
Hall Effect Current Sensor LEM: LA200-P TAMURA: S26P200D15Y VAC: T60404-N4646-X201 current conversion ratio: 1:2000 measure the output-current at a given input-current preparation: Apply R=60ohm between: SENSE_IR, SENSE_IU and GNDA SENSE_IS, SENSE_IV and GNDA Input-current source cable put through the hole once. Polarity markings: A positive measuring output-current is obtained on terminal M (pin 2), when the primary input-current flows in the direction of the arrow.			SENSE_IR, SENSE_IU : GNDA output-current @ 0A SENSE_IR, SENSE_IU : GNDA LEM_IR_output-current @ 2A SENSE_IR, SENSE_IU : GNDA LEM_IR_output-current @ -2A SENSE_IS, SENSE_IV : GNDA LEM_IS_output-current @ 0A SENSE_IS, SENSE_IV : GNDA LEM_IS_output-current @ 2A SENSE_IS, SENSE_IV : GNDA LEM_IS_output-current @ -2A	mA													-1,00	0,00	1,00											
																	0,90	1,00	1,10											
																	-1,10	-1,00	-0,90											
																	-1,00	0,00	1,00											
																	0,90	1,00	1,10											
																	-1,10	-1,00	-0,90											
CHG-RELAY contact resistance preparation: OUT_EN_INV:GND set to HIGH level OUT_EN_CONV:GND set to HIGH level REL1, REL2: contacts closed CHRG_N:GND to LOW REL1, REL2: contacts opened CHRG_N:GND to HIGH	2		R_RES:RUO@REL1, REL2: contacts opened R_RES:RUO@REL1, REL2: contacts closed S_RES:SVO@REL1, REL2: contacts opened S_RES:SVO@REL1, REL2: contacts closed	YES or NO													contacts opened													
																	contacts closed													
																	contacts opened													
																	contacts closed													

Test Requirement for PBX_BIDI GAA26800MX																		
1. All measuring instruments must be calibrated!!! 2. As an additional document, the circuit diagram of the PCBA is required. 3. All measuring points : reference points are described in kind of netnames, test points or component designator. 4. PBX_BIDI alternatively assembled with CONVERTER- or INVERTER-FUNCTIONALITY test cases only for PBX_BIDI, INVERTER -FUNCTIONALITY, GAA26800MX1, marked with note: 1 test cases only for PBX_BIDI, CONVERTER -FUNCTIONALITY, GAA26800MX2, marked with note: 2 5. Highly Accelerated Life Test, test cases required for HALT , marked with note: 3						Samples										Value range Lower Specification Limit Upper Specification Limit		
Test cases																		
Description	note	note	measuring point : reference point @ specified condition	unit											LSL	Typical	USL	
VRS, VST voltage gain calibration and transfer gain K3 (plausibility) check Linear Optocoupler GAA629CL1 Vendor Vishay: IL300-EF-X017T transfer gain K3 = 0.851 - 1.061 ± 0.5% Tamb = 0 °C to 75 °C Vendor Agilent / Avago: HCNR201 transfer gain K3 = 0.93 - 1.07	2		REF_SEC / GNDA (±10%) equation: 5V*0.4115*0.89111=1.83356V	mV											-2017,40	-1834,00	-1650,60	
			measuring point: DC_VRS / SGND (±10%) signal: VRS_DC_N / GND_SENSE												1852,20	2058,00	2263,80	
			measuring point: VRS / AGND (±25%) signal: VRS_OUT_DC_N / GNDA equation: 2.0576V*0.89111=1.8335V												1375,50	1834,00	2292,50	
			measuring point: VRS_N / AGND signal: VRS_OUT_N / GNDA												-1500,00	0,00	1500,00	
			transfer gain K3_VRS (plausibility) check proceeding: calculate with the following equation: K3_VRS=VRS_OUT_DC_N / (0.89111*VRS_DC_N)											0,80	1,00	1,10		
			measuring point: DC_VST / SGND (±10%) signal: VST_DC_N / GND_SENSE	mV											1852,20	2058,00	2263,80	
			measuring point: VST / AGND (+-25%) signal: VST_OUT_DC_N / GNDA equation: 2.0576V*0.89111=1.8335V												1375,50	1834,00	2292,50	
			measuring point: VST_N / AGND signal: VST_OUT_N / GNDA												-1500,00	0,00	1500,00	
					transfer gain K3_VST (plausibility) check proceeding: calculate with the following equation: K3_VST= VST_OUT_DC_N / (0.89111*VST_DC_N)											0,80	1,00	1,10
IGBT TEMPERATURE MEASUREMENT and transfer gain K3 (plausibility) check preparation: measure with connected resistor 5kohm, ±0.1% between NTC1 / NTC2			NTC1:NTC2 (1.86V±10%) measuring point: TEMP_IGBT / GNDA signal: TEMP_IGBT / GNDA equation: typical: (3.107V*0.89111)-0.7258=2.04V with gain range IL300: 0.8..1.2 min.: (0.8*2.77V)-0.7258=1.49V (-3% = 1.445V) max.: (1.2*2.77V)-0.7258=2.6V (+3% = 2.68V)	mV											1670,00	1860,00	2050,00	
															1445,00	2040,00	2680,00	
																1080,00	1200,00	1320,00
			InvTempUn (Addr.: 0x12) CnvTempUn (Addr.: 0x12) measuring point: TEMP_UN / GNDA signal: TEMP_UN / GNDA											2950,00	3110,00	3270,00		
			InvTempUin (Addr.: 0x14) CnvTempUin (Addr.: 0x14) preparation: measure with connected resistor 5kohm between NTC1 / NTC2 measuring point: NTC1 / SGND signal: NTC1 / GND_SENSE															
			transfer gain K3_TEMP (plausibility) check proceeding: calculate with the following equation: K3_TEMP= (TEMP_IGBT+(TEMP_UN*0.604)) / (NTC1*0.89111)												0,80	1,00	1,10	
DC-LINK VOLTAGE MEASUREMENT and transfer gain K3 (plausibility) check preparation: 1.) CALIBRATED precision DC voltage reference OUTPUT VOLTAGE: +1.2V ±0.2% max LOW NOISE: 10µVPP max (0.1Hz to 10Hz) conecetd to DCP_U_ME_1 / GND_SENSE 2.) short circuit is needed between DCN_U_ME_1 / GND_SENSE	1		InvUdcIUin (Addr.: 0x18) measuring point: DC_ME / GND_SENSE signal: DC_ME / GND_SENSE equation: typical: 1.2V*2.4864=3V	mV											2900,00	3000,00	3100,00	
			InvUdcIUout (Addr.: 0x1A) measuring point: UDCL / GNDA signal: UDCL / GNDA equation: typical: 3V*0.89111=2.673V with gain range IL300: 0.8..1.2 min.: 0.8*2.673V=2.138V (-3% = 2.07V) max.: 1.2*2.673V=3.208V (+3% = 3.22V)												2070,00	2673,00	3220,00	
			transfer gain K3_UDC (plausibility) check proceeding: calculate with the following equation: K3_UDC= UDCL / (0.89111*DC_ME)												0,80	1,00	1,10	

Test Requirement for PBX_BIDI GAA26800MX					Samples										Value range					
1. All measuring instruments must be calibrated!!! 2. As an additional document, the circuit diagram of the PCBA is required. 3. All measuring points : reference points are described in kind of netnames, test points or component designator. 4. PBX_BIDI alternatively assembled with CONVERTER- or INVERTER-FUNCTIONALITY test cases only for PBX_BIDI, INVERTER -FUNCTIONALITY, GAA26800MX1, marked with note: 1 test cases only for PBX_BIDI, CONVERTER -FUNCTIONALITY, GAA26800MX2, marked with note: 2 5. Highly Accelerated Life Test, test cases required for HALT , marked with note: 3															LSL			Typical		
Description		note	Test cases	measuring point : reference point @ specified condition	unit	Board Serial Number														
Hardware-dependent trimming values assumed measured values, see table above, calculated on values in [mV] to be storing in the EEPROM low bytes from trimming values must be written into the lower addresses. GAA26800MX1: I2C DEVICE Addr.: # 2 GAA26800MX2: I2C DEVICE Addr.: # 4 I2C bus lines: GAA26800MX1: I2C_SCL0_INV, I2C_DA0_INV GAA26800MX2: I2C_SCL0_CONV, I2C_DA0_CONV also to be storing, informations from the board assigned label:  S/N:MX1093400021 P/N:G1A26800MX1A-LF REV:2009-07-22  S/N:MX2093400014 P/N:G1A26800MX2A-LF REV:2009-07-22 GAA26800MX1: Package code: 0x00 = 20 (dez) GAA26800MX1: voltage_code: 0x02 = 4 (dez) GAA26800MX1: power code: 0x04 = 120 (dez) GAA26800MX1: Drive version number: 0x06 = 2 (dez) PCB serial number S/N: 0x0100..0x010F 16-byte; ASCII string; left-aligned; last bytes filled with spaces barcode; Otis definition; e.g. GAA26800MX1: "MX1093400021 " GAA26800MX2: "MX2093400014 " PCB part number P/N: 0x0120 bis 0x012F 16-byte; ASCII string; left-aligned; last bytes filled with spaces barcode; Otis definition; e.g. GAA26800MX1: "GAA26800MX1A-LF " GAA26800MX2: "GAA26800MX2A-LF " preparation: OUT_EN_INV:GND set to HIGH level OUT_EN_CONV:GND set to HIGH level				InvTempUref (Addr.: 0x10) CnvTempUref (Addr.: 0x10) values margin: 14000..15000..16000																
				InvTempUn (Addr.: 0x12) CnvTempUn (Addr.: 0x12) values margin: 1000..1202..1500																
				InvTempUin (Addr.: 0x14) CnvTempUin (Addr.: 0x14) values margin: 1613..3107..3596																
				InvTempUout (Addr.: 0x16) CnvTempUout (Addr.: 0x16) values margin: 1100..2769..3784 proceeding: calculate with the following equation: InvTempUout= TEMP_IGBT+9060/15000*InvTempUn CnvTempUout= TEMP_IGBT+9060/15000*CnvTempUn																
		1		InvUdclUin (Addr.: 0x18) values margin: 2743..3000..3242																
		2		CnvVrsUinDC (Addr.: 0x18) values margin: 4500..5000..5500 proceeding: calculate with the following equation: CnvVrsUinDC=VRS_DC_N*2.43																
		1		InvUdclUout (Addr.: 0x1A) values margin: 1870..2667..3412																
		2		CnvVrsUoutDC (Addr.: 0x1A) values margin: 3500..4455..5400 proceeding: calculate with the following equation: CnvVrsUoutDC=VRS_OUT_DC_N*2.43	mV															
		2		CnvVrsUout (Addr.: 0x1C) values margin: -1500..0..1500 constraint: if (VRS_OUT_N < 0) write (65536 - abs(VRS_OUT_N)) and if (VRS_OUT_N >= 0) then write CnvVrsUout equal to VRS_OUT_N with mV unit.																
		2		CnvVstUinDC (Addr.: 0x1E) values margin: 4500..5000..5500 proceeding: calculate with the following equation: CnvVstUinDC=VST_DC_N*2.43																
		2		CnvVstUoutDC (Addr: 0x20) values margin: 3500..4455..5400 proceeding: calculate with the following equation: CnvVstUoutDC=VST_OUT_DC_N*2.43																
		2		CnvVstUout (Addr: 0x22) values margin: -1500..0..1500 constraint: if (VST_OUT_N < 0) write (65536 - abs(VST_OUT_N)) and if (VST_OUT_N >= 0) then write CnvVstUout equal to VST_OUT_N with mV unit.																
		1		InvManufTestId (addr: 0x1C) must be set to enable the trimming parameter with set 0xDEC0 after end of hardware test&calibration addr: 0x1C data: C0 addr: 0x1D data: DE																
		2		CnvManufTestId (addr: 0x24) must be set to enable the trimming parameter with set 0xDEC0 after end of hardware test&calibration addr: 0x24 data: C0 addr: 0x25 data: DE	HEX															